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### Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	4
Number of Macrocells	64
Number of Gates	1250
Number of I/O	36
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/epm7064lc44-15yy">https://www.e-xfl.com/product-detail/intel/epm7064lc44-15yy</a>

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E and MAX 7000S devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2.0.0 and 3.0.0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* and the *Quartus Programmable Logic Development System & Software Data Sheet*.

## Functional Description

The MAX 7000 architecture includes the following elements:

- Logic array blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

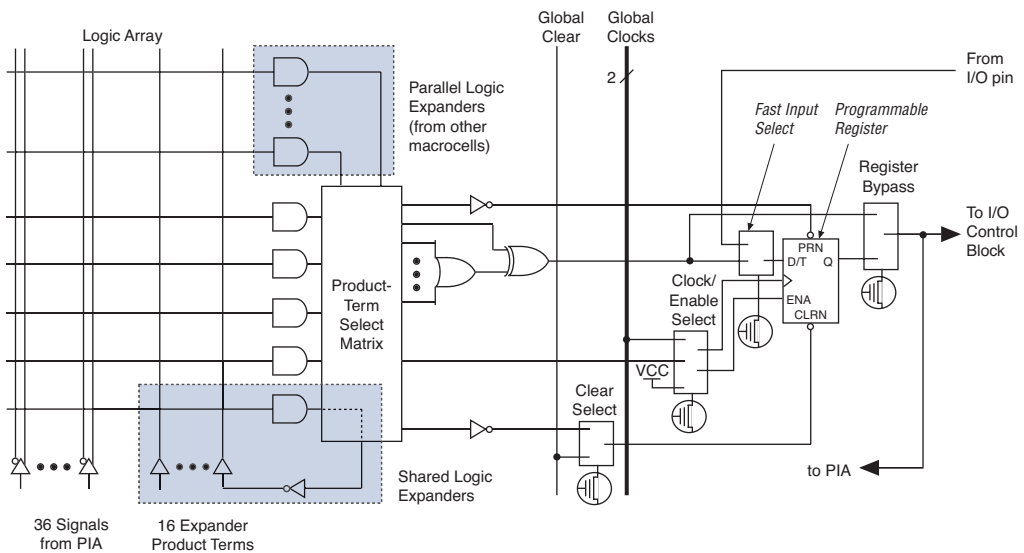
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

## Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

**Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell**





For more information on using the Jam language, refer to *AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor*.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

## Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

1. *Enter ISP.* The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
2. *Check ID.* Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
4. *Program.* Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
6. *Exit ISP.* An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

## Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

### *Programming a Single MAX 7000S Device*

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where:  $t_{PROG}$  = Programming time  
 $t_{PPULSE}$  = Sum of the fixed times to erase, program, and verify the EEPROM cells  
 $Cycle_{PTCK}$  = Number of TCK cycles to program a device  
 $f_{TCK}$  = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where:  $t_{VER}$  = Verify time  
 $t_{VPULSE}$  = Sum of the fixed times to verify the EEPROM cells  
 $Cycle_{VTCK}$  = Number of TCK cycles to verify a device

The programming times described in [Tables 6 through 8](#) are associated with the worst-case method using the enhanced ISP algorithm.

**Table 6. MAX 7000S  $t_{PULSE}$  &  $Cycle_{TCK}$  Values**

Device	Programming		Stand-Alone Verification	
	$t_{PULSE}$ (s)	$Cycle_{PTCK}$	$t_{VPULSE}$ (s)	$Cycle_{VTCK}$
EPM7032S	4.02	342,000	0.03	200,000
EPM7064S	4.50	504,000	0.03	308,000
EPM7128S	5.11	832,000	0.03	528,000
EPM7160S	5.35	1,001,000	0.03	640,000
EPM7192S	5.71	1,192,000	0.03	764,000
EPM7256S	6.43	1,603,000	0.03	1,024,000

[Tables 7](#) and [8](#) show the in-system programming and stand alone verification times for several common test clock frequencies.

**Table 7. MAX 7000S In-System Programming Times for Different Test Clock Frequencies**

Device	$f_{TCK}$								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	s
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	s
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	s
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	s
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	s

**Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies**

Device	$f_{TCK}$								Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	s
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	s
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	s
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	s
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	s
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	s

By using an external 5.0-V pull-up resistor, output pins on MAX 7000S devices can be set to meet 5.0-V CMOS input voltages. When  $V_{CCIO}$  is 3.3 V, setting the open drain option will turn off the output pull-up transistor, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages. When  $V_{CCIO}$  is 5.0 V, setting the output drain option is not necessary because the pull-up transistor will already turn off when the pin exceeds approximately 3.8 V, allowing the external pull-up resistor to pull the output high enough to meet 5.0-V CMOS input voltages.

### Slew-Rate Control

The output buffer for each MAX 7000E and MAX 7000S I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. In MAX 7000E devices, when the Turbo Bit is turned off, the slew rate is set for low noise performance. For MAX 7000S devices, each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis.

## Programming with External Hardware

MAX 7000 devices can be programmed on Windows-based PCs with the Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs a continuity check to ensure adequate electrical contact between the adapter and the device.



For more information, see the [\*Altera Programming Hardware Data Sheet\*](#).

The Altera development system can use text- or waveform-format test vectors created with the Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation. Moreover, Data I/O, BP Microsystems, and other programming hardware manufacturers also provide programming support for Altera devices.



For more information, see the [\*Programming Hardware Manufacturers\*](#).

## IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000 devices support JTAG BST circuitry as specified by IEEE Std. 1149.1-1990. [Table 9](#) describes the JTAG instructions supported by the MAX 7000 family. The pin-out tables (see the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information) show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

**Table 9. MAX 7000 JTAG Instructions**

JTAG Instruction	Devices	Description
SAMPLE/PRELOAD	EPM7128S EPM7160S EPM7192S EPM7256S	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern output at the device pins.
EXTEST	EPM7128S EPM7160S EPM7192S EPM7256S	Allows the external circuitry and board-level interconnections to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through a selected device to adjacent devices during normal device operation.
IDCODE	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
ISP Instructions	EPM7032S EPM7064S EPM7128S EPM7160S EPM7192S EPM7256S	These instructions are used when programming MAX 7000S devices via the JTAG ports with the MasterBlaster, ByteBlasterMV, BitBlaster download cable, or using a Jam File (.jam), Jam Byte-Code file (.jbc), or Serial Vector Format file (.svf) via an embedded processor or test equipment.



## Operating Conditions

Tables 13 through 18 provide information about absolute maximum ratings, recommended operating conditions, operating conditions, and capacitance for 5.0-V MAX 7000 devices.

**Table 13. MAX 7000 5.0-V Device Absolute Maximum Ratings** *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply voltage	With respect to ground (2)	–2.0	7.0	V
$V_I$	DC input voltage		–2.0	7.0	V
$I_{OUT}$	DC output current, per pin		–25	25	mA
$T_{STG}$	Storage temperature	No bias	–65	150	°C
$T_{AMB}$	Ambient temperature	Under bias	–65	135	°C
$T_J$	Junction temperature	Ceramic packages, under bias		150	°C
		PQFP and RQFP packages, under bias		135	°C

**Table 14. MAX 7000 5.0-V Device Recommended Operating Conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CCINT}$	Supply voltage for internal logic and input buffers	(3), (4), (5)	4.75 (4.50)	5.25 (5.50)	V
$V_{CCIO}$	Supply voltage for output drivers, 5.0-V operation	(3), (4)	4.75 (4.50)	5.25 (5.50)	V
	Supply voltage for output drivers, 3.3-V operation	(3), (4), (6)	3.00 (3.00)	3.60 (3.60)	V
$V_{CCISP}$	Supply voltage during ISP	(7)	4.75	5.25	V
$V_I$	Input voltage		–0.5 (8)	$V_{CCINT} + 0.5$	V
$V_O$	Output voltage		0	$V_{CCIO}$	V
$T_A$	Ambient temperature	For commercial use	0	70	°C
		For industrial use	–40	85	°C
$T_J$	Junction temperature	For commercial use	0	90	°C
		For industrial use	–40	105	°C
$t_R$	Input rise time			40	ns
$t_F$	Input fall time			40	ns

**Table 15. MAX 7000 5.0-V Device DC Operating Conditions** *Note (9)*

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{IH}$	High-level input voltage		2.0	$V_{CCINT} + 0.5$	V
$V_{IL}$	Low-level input voltage		-0.5 (8)	0.8	V
$V_{OH}$	5.0-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 4.75$ V (10)	2.4		V
	3.3-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 3.00$ V (10)	2.4		V
	3.3-V high-level CMOS output voltage	$I_{OH} = -0.1$ mA DC, $V_{CCIO} = 3.0$ V (10)	$V_{CCIO} - 0.2$		V
$V_{OL}$	5.0-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 4.75$ V (11)		0.45	V
	3.3-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 3.00$ V (11)		0.45	V
	3.3-V low-level CMOS output voltage	$I_{OL} = 0.1$ mA DC, $V_{CCIO} = 3.0$ V (11)		0.2	V
$I_I$	Leakage current of dedicated input pins	$V_I = -0.5$ to $5.5$ V (11)	-10	10	$\mu$ A
$I_{OZ}$	I/O pin tri-state output off-state current	$V_I = -0.5$ to $5.5$ V (11), (12)	-40	40	$\mu$ A

**Table 16. MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096 Devices** *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		12	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		12	pF

**Table 17. MAX 7000 5.0-V Device Capacitance: MAX 7000E Devices** *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		15	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		15	pF

**Table 18. MAX 7000 5.0-V Device Capacitance: MAX 7000S Devices** *Note (13)*

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Dedicated input pin capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		10	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		10	pF

**Table 20. MAX 7000 & MAX 7000E Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade -6		Speed Grade -7		Unit
			Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.4		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.4		0.5	ns
$t_{FIN}$	Fast input delay	(2)		0.8		1.0	ns
$t_{SEXP}$	Shared expander delay			3.5		4.0	ns
$t_{PEXP}$	Parallel expander delay			0.8		0.8	ns
$t_{LAD}$	Logic array delay			2.0		3.0	ns
$t_{LAC}$	Logic control array delay			2.0		3.0	ns
$t_{OE}$	Internal output enable delay	(2)				2.0	ns
$t_{OD1}$	Output buffer and pad delay Slow slew rate = off, $V_{CCIO} = 5.0$ V	$C1 = 35$ pF		2.0		2.0	ns
$t_{OD2}$	Output buffer and pad delay Slow slew rate = off, $V_{CCIO} = 3.3$ V	$C1 = 35$ pF (7)		2.5		2.5	ns
$t_{OD3}$	Output buffer and pad delay Slow slew rate = on, $V_{CCIO} = 5.0$ V or 3.3 V	$C1 = 35$ pF (2)		7.0		7.0	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 5.0$ V	$C1 = 35$ pF		4.0		4.0	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off, $V_{CCIO} = 3.3$ V	$C1 = 35$ pF (7)		4.5		4.5	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0$ V or 3.3 V	$C1 = 35$ pF (2)		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5$ pF		4.0		4.0	ns
$t_{SU}$	Register setup time		3.0		3.0		ns
$t_H$	Register hold time		1.5		2.0		ns
$t_{FSU}$	Register setup time of fast input	(2)	2.5		3.0		ns
$t_{FH}$	Register hold time of fast input	(2)	0.5		0.5		ns
$t_{RD}$	Register delay			0.8		1.0	ns
$t_{COMB}$	Combinatorial delay			0.8		1.0	ns
$t_{JC}$	Array clock delay			2.5		3.0	ns
$t_{EN}$	Register enable time			2.0		3.0	ns
$t_{GLOB}$	Global control delay			0.8		1.0	ns
$t_{PRE}$	Register preset time			2.0		2.0	ns
$t_{CLR}$	Register clear time			2.0		2.0	ns
$t_{PIA}$	PIA delay			0.8		1.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		10.0	ns

**Table 21. MAX 7000 & MAX 7000E External Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-10P)		MAX 7000 (-10) MAX 7000E (-10)		
			Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns
t <sub>SU</sub>	Global clock setup time		7.0		8.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.5		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		5.0		5	ns
t <sub>CH</sub>	Global clock high time		4.0		4.0		ns
t <sub>CL</sub>	Global clock low time		4.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time		2.0		3.0		ns
t <sub>AH</sub>	Array clock hold time		3.0		3.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns
t <sub>ACH</sub>	Array clock high time		4.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		4.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	4.0		4.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			10.0		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	100.0		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			10.0		10.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(5)	100.0		100.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	125.0		125.0		MHz

**Table 24. MAX 7000 & MAX 7000E Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade				Unit
			MAX 7000E (-12P)		MAX 7000 (-12) MAX 7000E (-12)		
			Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			1.0		2.0	ns
$t_{IO}$	I/O input pad and buffer delay			1.0		2.0	ns
$t_{FIN}$	Fast input delay	(2)		1.0		1.0	ns
$t_{SEXP}$	Shared expander delay			7.0		7.0	ns
$t_{PEXP}$	Parallel expander delay			1.0		1.0	ns
$t_{LAD}$	Logic array delay			7.0		5.0	ns
$t_{LAC}$	Logic control array delay			5.0		5.0	ns
$t_{IOE}$	Internal output enable delay	(2)		2.0		2.0	ns
$t_{OD1}$	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 5.0$ V	$C1 = 35$ pF		1.0		3.0	ns
$t_{OD2}$	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3$ V	$C1 = 35$ pF (7)		2.0		4.0	ns
$t_{OD3}$	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0$ V or 3.3 V	$C1 = 35$ pF (2)		5.0		7.0	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0$ V	$C1 = 35$ pF		6.0		6.0	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3$ V	$C1 = 35$ pF (7)		7.0		7.0	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0$ V or 3.3 V	$C1 = 35$ pF (2)		10.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5$ pF		6.0		6.0	ns
$t_{SU}$	Register setup time		1.0		4.0		ns
$t_H$	Register hold time		6.0		4.0		ns
$t_{FSU}$	Register setup time of fast input	(2)	4.0		2.0		ns
$t_{FH}$	Register hold time of fast input	(2)	0.0		2.0		ns
$t_{RD}$	Register delay			2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			2.0		1.0	ns
$t_{IC}$	Array clock delay			5.0		5.0	ns
$t_{EN}$	Register enable time			7.0		5.0	ns
$t_{GLOB}$	Global control delay			2.0		0.0	ns
$t_{PRE}$	Register preset time			4.0		3.0	ns
$t_{CLR}$	Register clear time			4.0		3.0	ns
$t_{PIA}$	PIA delay			1.0		1.0	ns
$t_{LPA}$	Low-power adder	(8)		12.0		12.0	ns

**Table 26. MAX 7000 & MAX 7000E Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-15		-15T		-20		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			2.0		2.0		3.0	ns
$t_{IO}$	I/O input pad and buffer delay			2.0		2.0		3.0	ns
$t_{FIN}$	Fast input delay	(2)		2.0		–		4.0	ns
$t_{SEXP}$	Shared expander delay			8.0		10.0		9.0	ns
$t_{PEXP}$	Parallel expander delay			1.0		1.0		2.0	ns
$t_{LAD}$	Logic array delay			6.0		6.0		8.0	ns
$t_{LAC}$	Logic control array delay			6.0		6.0		8.0	ns
$t_{IOE}$	Internal output enable delay	(2)		3.0		–		4.0	ns
$t_{OD1}$	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$		4.0		4.0		5.0	ns
$t_{OD2}$	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ (7)		5.0		–		6.0	ns
$t_{OD3}$	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ (2)		8.0		–		9.0	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$		6.0		6.0		10.0	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ (7)		7.0		–		11.0	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ (2)		10.0		–		14.0	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		6.0		6.0		10.0	ns
$t_{SU}$	Register setup time		4.0		4.0		4.0		ns
$t_H$	Register hold time		4.0		4.0		5.0		ns
$t_{FSU}$	Register setup time of fast input	(2)	2.0		–		4.0		ns
$t_{FH}$	Register hold time of fast input	(2)	2.0		–		3.0		ns
$t_{RD}$	Register delay			1.0		1.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.0		1.0		1.0	ns
$t_{IC}$	Array clock delay			6.0		6.0		8.0	ns
$t_{EN}$	Register enable time			6.0		6.0		8.0	ns
$t_{GLOB}$	Global control delay			1.0		1.0		3.0	ns
$t_{PRE}$	Register preset time			4.0		4.0		4.0	ns
$t_{CLR}$	Register clear time			4.0		4.0		4.0	ns
$t_{PIA}$	PIA delay			2.0		2.0		3.0	ns
$t_{LPA}$	Low-power adder	(8)		13.0		15.0		15.0	ns

**Table 27. EPM7032S External Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

**Table 28. EPM7032S Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.2		0.2		0.3		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.2		0.2		0.3		0.5	ns
$t_{FIN}$	Fast input delay			2.2		2.1		2.5		1.0	ns
$t_{SEXP}$	Shared expander delay			3.1		3.8		4.6		5.0	ns
$t_{PEXP}$	Parallel expander delay			0.9		1.1		1.4		0.8	ns
$t_{LAD}$	Logic array delay			2.6		3.3		4.0		5.0	ns
$t_{LAC}$	Logic control array delay			2.5		3.3		4.0		5.0	ns
$t_{IOE}$	Internal output enable delay			0.7		0.8		1.0		2.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		0.4		1.5	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		0.9		2.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		5.4		5.5	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
$t_{SU}$	Register setup time		0.8		1.0		1.3		2.0		ns
$t_H$	Register hold time		1.7		2.0		2.5		3.0		ns
$t_{FSU}$	Register setup time of fast input		1.9		1.8		1.7		3.0		ns
$t_{FH}$	Register hold time of fast input		0.6		0.7		0.8		0.5		ns
$t_{RD}$	Register delay			1.2		1.6		1.9		2.0	ns
$t_{COMB}$	Combinatorial delay			0.9		1.1		1.4		2.0	ns
$t_{IC}$	Array clock delay			2.7		3.4		4.2		5.0	ns
$t_{EN}$	Register enable time			2.6		3.3		4.0		5.0	ns
$t_{GLOB}$	Global control delay			1.6		1.4		1.7		1.0	ns
$t_{PRE}$	Register preset time			2.0		2.4		3.0		3.0	ns
$t_{CLR}$	Register clear time			2.0		2.4		3.0		3.0	ns

**Table 33. EPM7160S External Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>ACNT</sub>	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

**Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade								Unit
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns
$t_{IO}$	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns
$t_{FIN}$	Fast input delay			2.6		3.2		1.0		2.0	ns
$t_{SEXP}$	Shared expander delay			3.6		4.3		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.0		1.3		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.8		3.4		5.0		6.0	ns
$t_{LAC}$	Logic control array delay			2.8		3.4		5.0		6.0	ns
$t_{IOE}$	Internal output enable delay			0.7		0.9		2.0		3.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns
$t_{SU}$	Register setup time		1.0		1.2		2.0		4.0		ns
$t_H$	Register hold time		1.6		2.0		3.0		4.0		ns
$t_{FSU}$	Register setup time of fast input		1.9		2.2		3.0		2.0		ns
$t_{FH}$	Register hold time of fast input		0.6		0.8		0.5		1.0		ns
$t_{RD}$	Register delay			1.3		1.6		2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.0		1.3		2.0		1.0	ns
$t_{IC}$	Array clock delay			2.9		3.5		5.0		6.0	ns
$t_{EN}$	Register enable time			2.8		3.4		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.0		2.4		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.4		3.0		3.0		4.0	ns



**Table 36. EPM7192S Internal Timing Parameters (Part 2 of 2)** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
$t_H$	Register hold time		1.7		3.0		4.0		ns
$t_{FSU}$	Register setup time of fast input		2.3		3.0		2.0		ns
$t_{FH}$	Register hold time of fast input		0.7		0.5		1.0		ns
$t_{RD}$	Register delay			1.4		2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.2		2.0		1.0	ns
$t_{IC}$	Array clock delay			3.2		5.0		6.0	ns
$t_{EN}$	Register enable time			3.1		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.5		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.7		3.0		4.0	ns
$t_{CLR}$	Register clear time			2.7		3.0		4.0	ns
$t_{PIA}$	PIA delay	(7)		2.4		1.0		2.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		11.0		13.0	ns

**Notes to tables:**

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$  and  $t_{CPW}$  parameters for macrocells running in the low-power mode.

**Table 38. EPM7256S Internal Timing Parameters** *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-7		-10		-15		
			Min	Max	Min	Max	Min	Max	
$t_{IN}$	Input pad and buffer delay			0.3		0.5		2.0	ns
$t_{IO}$	I/O input pad and buffer delay			0.3		0.5		2.0	ns
$t_{FIN}$	Fast input delay			3.4		1.0		2.0	ns
$t_{SEXP}$	Shared expander delay			3.9		5.0		8.0	ns
$t_{PEXP}$	Parallel expander delay			1.1		0.8		1.0	ns
$t_{LAD}$	Logic array delay			2.6		5.0		6.0	ns
$t_{LAC}$	Logic control array delay			2.6		5.0		6.0	ns
$t_{IOE}$	Internal output enable delay			0.8		2.0		3.0	ns
$t_{OD1}$	Output buffer and pad delay	C1 = 35 pF		0.5		1.5		4.0	ns
$t_{OD2}$	Output buffer and pad delay	C1 = 35 pF (6)		1.0		2.0		5.0	ns
$t_{OD3}$	Output buffer and pad delay	C1 = 35 pF		5.5		5.5		8.0	ns
$t_{ZX1}$	Output buffer enable delay	C1 = 35 pF		4.0		5.0		6.0	ns
$t_{ZX2}$	Output buffer enable delay	C1 = 35 pF (6)		4.5		5.5		7.0	ns
$t_{ZX3}$	Output buffer enable delay	C1 = 35 pF		9.0		9.0		10.0	ns
$t_{XZ}$	Output buffer disable delay	C1 = 5 pF		4.0		5.0		6.0	ns
$t_{SU}$	Register setup time		1.1		2.0		4.0		ns
$t_H$	Register hold time		1.6		3.0		4.0		ns
$t_{FSU}$	Register setup time of fast input		2.4		3.0		2.0		ns
$t_{FH}$	Register hold time of fast input		0.6		0.5		1.0		ns
$t_{RD}$	Register delay			1.1		2.0		1.0	ns
$t_{COMB}$	Combinatorial delay			1.1		2.0		1.0	ns
$t_{IC}$	Array clock delay			2.9		5.0		6.0	ns
$t_{EN}$	Register enable time			2.6		5.0		6.0	ns
$t_{GLOB}$	Global control delay			2.8		1.0		1.0	ns
$t_{PRE}$	Register preset time			2.7		3.0		4.0	ns
$t_{CLR}$	Register clear time			2.7		3.0		4.0	ns
$t_{PIA}$	PIA delay	(7)		3.0		1.0		2.0	ns
$t_{LPA}$	Low-power adder	(8)		10.0		11.0		13.0	ns

**Notes to tables:**

- (1) These values are specified under the recommended operating conditions shown in [Table 14](#). See [Figure 13](#) for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The  $t_{LPA}$  parameter must be added to this minimum width if the clear or reset signal incorporates the  $t_{LAD}$  parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPTW}$  parameters for macrocells running in the low-power mode.

## Power Consumption

Supply power (P) versus frequency ( $f_{MAX}$  in MHz) for MAX 7000 devices is calculated with the following equation:

$$P = P_{INT} + P_{IO} = I_{CCINT} \times V_{CC} + P_{IO}$$

The  $P_{IO}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in [Application Note 74 \(Evaluating Power for Altera Devices\)](#).

The  $I_{CCINT}$  value, which depends on the switching frequency and the application logic, is calculated with the following equation:

$$I_{CCINT} =$$

$$A \times MC_{TON} + B \times (MC_{DEV} - MC_{TON}) + C \times MC_{USED} \times f_{MAX} \times \text{tog}_{LC}$$

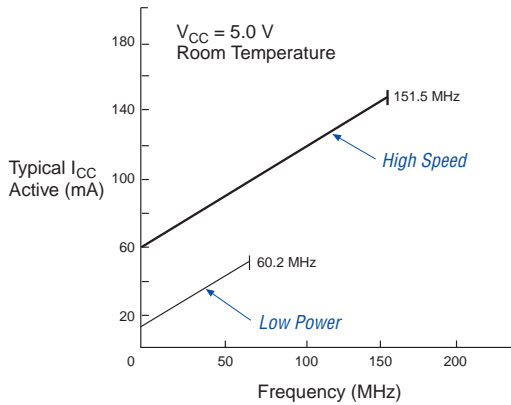
The parameters in this equation are shown below:

$MC_{TON}$	=	Number of macrocells with the Turbo Bit option turned on, as reported in the MAX+PLUS II Report File (.rpt)
$MC_{DEV}$	=	Number of macrocells in the device
$MC_{USED}$	=	Total number of macrocells in the design, as reported in the MAX+PLUS II Report File (.rpt)
$f_{MAX}$	=	Highest clock frequency to the device
$\text{tog}_{LC}$	=	Average ratio of logic cells toggling at each clock (typically 0.125)
A, B, C	=	Constants, shown in <a href="#">Table 39</a>

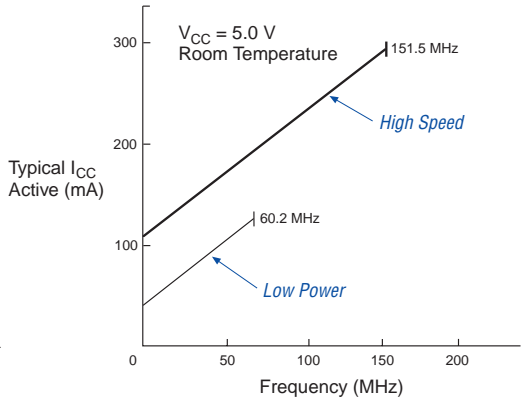
Figure 14 shows typical supply current versus frequency for MAX 7000 devices.

Figure 14.  $I_{CC}$  vs. Frequency for MAX 7000 Devices (Part 1 of 2)

EPM7032



EPM7064



EPM7096

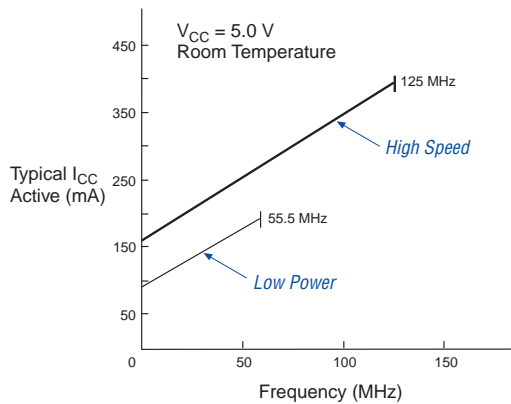
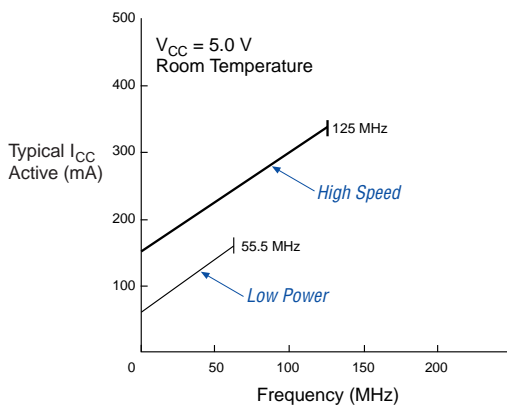
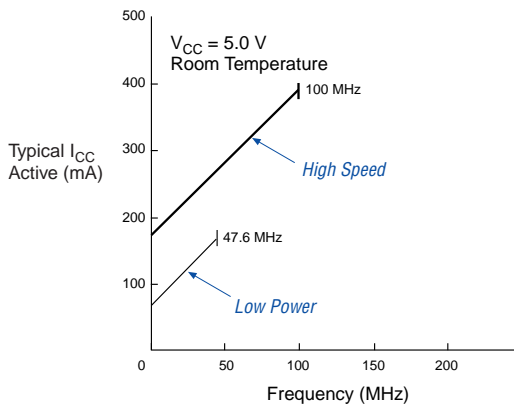


Figure 14.  $I_{CC}$  vs. Frequency for MAX 7000 Devices (Part 2 of 2)

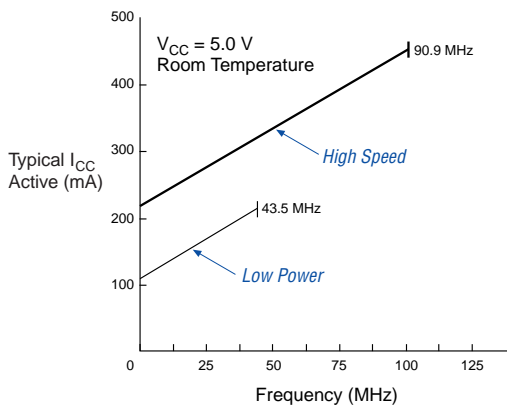
EPM7128E



EPM7160E



EPM7192E



EPM7256E

